

Physical Explanations

AQL

Acceptable Quality Level (see chapter "Quality Data")

B, b Base, base terminal

C, c Collector, collector terminal

С

Capacitances

The transistor equivalent circuit (see chapter "Transistor Equivalent Circuit") shows the different capacitances in a transistor. Additionally, there are capacitances between terminals, inside as well as outside the package. All these capacitances have its effect only at high frequencies. Here, the actual operating capacitances are important, but not the equivalent circuit capacitances. They can be best explained with y coefficients.

Ci

Short-circuit input capacitance $C_{11} = C_i$

It is an imaginary part of the short-circuit input admittance y_{11} (= y_i) divided by a factor j ω .

The values of capacitances are circuit-configuration dependent; therefore, a further subscript (e, b or c) is added with the concerned capacitance to designate the orientation.

 C_{ib}

Short-circuit input capacitance in common-base configuration

$$C_{_{11b}} = C_{_{ib}} = \frac{1}{j\omega} \text{ Im } (y_{_{ib}})$$

C_{ie}

Short-circuit input capacitance in common-emitter configuration

$$C_{_{11e}} = C_{_{ie}} = \frac{1}{j\omega} Im (y_{_{ie}})$$

C_{issg1}

Gate 1-input capacitance in common-source configuration

C_{issg2}

Gate 2-input capacitance in common-source configuration

 C_{o}

Short-circuit output capacitance

C_{ob}

Short-circuit output capacitance in common-base configuration

$$C_{22b} = C_{ob} = \frac{1}{j\omega} \text{ Im } (y_{ob})$$

Coe

Short-circuit output capacitance in common-emitter configuration.

$$C_{22e} = C_{oe} = \frac{1}{i\omega} Im (y_{oe})$$

Coss

Output capacitance in common-source configuration

C_{rss}

Feedback capacitance in common-source configuration

C_{rb}

Feedback capacitance in common-base configuration

$$C_{rb} = C_{12b} = \frac{1}{j\omega} Im (y_{rb})$$

C_{re}

Feedback capacitance in common-emitter configuration

$$C_{re} = C_{12e} = \frac{1}{j\omega} Im (y_{re})$$

Additional **capacitances** are given in the data sheet. They can be deducted from the direct measurements given below.

 C_{cb}

Capacitance between collector and base without parasitic capacitances

C_{CBO}

Capacitance between collector and base with open emitter. It can be measured by applying reverse bias to its terminals.

The following relationship is also valid:

 $C_{CBO} \approx C_{oe} \approx C_{ob}$

(Different configurations, but approximately the same values)

 C_{eb}

Capacitance between emitter and base without parasitic capacitances

C_{EBO}

Capacitance between emitter and base having an open collector. Measurement is carried out by applying reverse bias to its terminals



The following relationship is also valid:

$$C_{EBO} \approx C_{ie} \approx C_{ib}$$

(Different configurations, but approximately the same values)

C_L Load capacitance

C_p Parallel capacitance Package capacitance

D Drain

d_{iM} Signal-to-intermodulation ratio

E, e

Emitter

E_L Inductive energy

F

Noise figure

For a given frequency and bandwidth, the noise figure is the ratio of the total noise power, p_2 , delivered to the output termination, to the portion (G_p p_1) that is contributed by the input power, p_1 , given from the signal source whose noise temperature is standard ($T_0 = 290$ K) at all frequencies

$$F = \frac{p_2}{G_p p_1}$$

If this ratio is given in decibel, it is valid that:

 $\frac{F}{dB} = 10 \ lg \frac{p_2}{G_p \ p_1}$

The noise figure is given for a specified operating point, a specified generator (source) resistance and a specified frequency or frequency range

f

Frequency

Fc Noise figure for mixer

fg, f_{-3dB} Cut-off frequency

 $\begin{array}{l} f_{hfe} \\ h_{fe}\text{-cut-off frequency} \\ (\beta\text{-cut-off frequency, } f_{\beta}) \end{array}$

The frequency at which the modulus of the current amplification factor ($\rm h_{fe})$ has decreased below 0.707 times the frequency (1 kHz)

f_{IM} Intermodulation frequency

f_{max}

Maximum frequency of oscillation

Frequency by which the power gain of a transistor assumes the value of one due to conjugately matching of input and output.

f_T

Gain bandwidth product, transition frequency

The product of the modulus of the common-emitter, small-signal short-circuit forward current transfer ratio, and the frequency of measurement f_M . This frequency is chosen because h_{fe} decreases at a slope of approximately 6 dB per octave.

The associated angular frequency

 $\omega_{\rm T}$ = 2 π f_T

is defined as the reciprocal value of transit time minority carriers through the base region.

Conductance

G, g Gate

G_G Generator conductance

Short-circuit input conductance

gib

Input conductance in common-base configuration, short circuit at output $g_{ib} = Re(y_{ib})$

g_{ie}

Input conductance in common-emitter configuration, short circuit at output $g_{ie} = \text{Re}(y_{ie})$

90 Short-circuit output conductance

 g_{ob} Output conductance in common-base configuration, short circuit at input $g_{ob} = \text{Re}(y_{ob})$

 g_{oe} Output conductance in common-emitter configuration short circuit at input $g_{oe} = \text{Re}(y_{oe})$

G_{pb} Power gain in common-base configuration

G_{pe} Power gain in common-emitter configuration

G_{ps} Power gain in common-source configuration



g_r

Short-circuit reverse conductance

G_v Unilateral gain

 h_{FE}

DC forward-current transfer ratio in common-emitter configuration

It is the ratio of the collector current, I_C , to the base current, I_B , for specified values of V_{CE} and I_C .

It is also denoted by the symbol B.

h

The hybrid matrix is an arrangement of h parameters given as follows:

$$\mathbf{h} = \begin{pmatrix} \mathbf{h}_{i} & \mathbf{h}_{r} \\ \mathbf{h}_{f} & \mathbf{h}_{o} \end{pmatrix} = \begin{pmatrix} \mathbf{h}_{11} & \mathbf{h}_{12} \\ \mathbf{h}_{21} & \mathbf{h}_{22} \end{pmatrix}$$

These h parameters are used mostly in the audio frequency range. They are valid only for a specified operating point and frequency. Usually, this frequency is 1 kHz and the corresponding h parameters are having real values only.

The following electrical characteristics can be calculated from the parameters mentioned above



Figure 1.

Current amplification

$$G_i = \frac{\underline{I}_2}{\underline{I}_1} = \frac{h_{21} \ G_L}{h_{22} + G_L} = \frac{h_{21}}{1 + h_{22} \ IG_L}$$

Voltage amplification

$$G_{u} = \frac{\underline{V}_{1}}{\underline{V}_{1}} = \frac{-h_{21}}{h_{11}(h_{22} + G_{L}) - h_{12} h_{21}}$$

Input resistance

$$r_{_{in}} = \frac{\underline{V}_{_{1}}}{\underline{I}_{_{1}}} = h_{_{11}} - \frac{h_{_{12}} h_{_{21}}}{h_{_{22}} + G_{_{L}}}$$

Output conductance

$$g_{\text{out}} = \frac{\underline{I}_2}{\underline{V}_2} = h_{22} - \frac{h_{12} \ h_{21}}{h_{11} + R_G}$$

Power gain

$$\begin{aligned} G_{p} &= \frac{P_{out}}{P_{in}} = G_{L} r_{in} |A_{u}|^{2} \\ &= G_{L} \frac{h_{21}^{2}}{[h_{11}(h_{22} + G_{L}) - h_{12} h_{21}] (h_{22} + G_{L})} \end{aligned}$$

The h parameters are the coefficients of two-port network equations given in hybrid form:

$$\underline{\mathbf{V}}_1 = \mathbf{h}_i \ \underline{\mathbf{I}}_1 + \mathbf{h}_r \ \underline{\mathbf{V}}_2 = \mathbf{h}_{11} \ \underline{\mathbf{I}}_1 + \mathbf{h}_{12} \ \underline{\mathbf{V}}_2$$
$$\underline{\mathbf{I}}_2 = \mathbf{h}_f \ \underline{\mathbf{I}}_1 + \mathbf{h}_0 \ \underline{\mathbf{V}}_2 = \mathbf{h}_{21} \ \underline{\mathbf{I}}_1 + \mathbf{h}_{22} \ \underline{\mathbf{V}}_2$$

h_i Short-circuit input impedance

$$\mathbf{h}_{i} = \mathbf{h}_{11} = \left(\frac{\underline{\mathbf{V}}_{1}}{\underline{\mathbf{I}}_{1}}\right) \, \underline{\mathbf{V}}_{2} = \mathbf{0}$$

Parameter values are circuit-configuration dependent; therefore, a further subscript (e, b or c) is used to identify the circuit configuration.

h_{ib}

Short-circuit input resistance in common-base config-uration (small-signal value)

h_{ie}

Short-circuit input resistance in common-emitter configuration (small-signal value)

Open-circuit reverse-voltage transfer ratio

$$\mathbf{h}_{\mathrm{r}} = \mathbf{h}_{12} = \left(\frac{\underline{\mathbf{V}}_{1}}{\underline{\mathbf{V}}_{2}}\right) \underline{\mathbf{I}}_{1} = \mathbf{0}$$

h_{rb}

Open-circuit reverse-voltage transfer ratio in common-base configuration (small-signal value)

h_{re}

Open-circuit reverse-voltage transfer ratio in common-emitter configuration (small-signal value)

h_f

Short-circuit forward-current transfer ratio

$$\mathbf{h}_{\mathrm{f}} = \mathbf{h}_{21} = \left(\frac{\underline{\mathbf{I}}_2}{\underline{\mathbf{I}}_1}\right) \quad \underline{\mathbf{V}}_2 = \mathbf{0}$$

h_{fb}

Short-circuit forward-current transfer ratio in common-base configuration (small-signal value)

h_{fe}

Short-circuit forward-current transfer ratio in common-emitter configuration (small-signal value)

This is the ratio of the alternating collector current, i_c , to the alterning base current, i_b , for small signals whose output is short-circuited to a.c. This is also known as β .

In technical data sheets, this parameter is given with 1 kHz sine wave for a specified operating point. This quantity is also known as the current amplification factor.

ho

Open-circuit output admittance

$$\mathbf{h}_0 = \mathbf{h}_{22} = \left(\frac{\underline{\mathbf{I}}_1}{\underline{\mathbf{V}}_{22}}\right) \, \underline{\mathbf{I}}_1 = 0$$

h_{ob}

Open-circuit output conductance in common-base configuration (small-signal value)

h_{oe}

Open-circuit output conductance in common-emitter configuration (small-signal value)

 I_B

DC base current

I_{BM} Peak base current

I_C DC collector current

 I_{CBO}

Collector cut-off current, with open emitter

The cut-off current is the reverse current flowing through the junction(s) (base-emitter or base-collector) of a transistor. By applying reverse bias across its terminals, the third terminal is open-circuited or otherwise specified. This is also known as leakage current.

Collector-base cut-off current, $I_{CBO},$ and collector-base $V_{CBO},$ with open emitter, i.e., I_E = 0 A







Collector-emitter, cut-off current, I_{CEO} , and collector-emitter voltage, V_{CEO} , with open base, i.e., $I_B = 0$



Figure 3.

ICER

Collector cut-off current, with a resistor R_{BE} connected between base and emitter

Collector-emitter cut-off current, I_{CER} , and collector-emitter voltage, V_{CER} having the resistance connected between base and emitter. The appropriate value of R_{BE} referring to V_{CER} is also given in the technical data sheets. For higher values of R_{BE} , the values of V_{CEO} and I_{CEO} are valid.





I_{CES} Collector cut-off current, short circuit between base and emitter

Collector cut-off current, $I_{CES} = I_{CBS}$, and collector-emitter voltage,

 $V_{CES} = V_{CBS}$, with base emitter short-circuited



Figure 5.





 I_{CEV}

Collector cut-off current with reverse base-emitter voltage

Collector-emitter cut-off current, I_{CEV} , and collectoremitter voltage, V_{CEV} , when the applied voltage between base and emitter is reverse biased



Figure 6.

ICEX

Collector cut-off current with forward base-emitter voltage

Collector-emitter cut-off current, $\mathsf{I}_{\mathsf{CEX},}$ when the applied voltage between base and emitter is forward biased

The value of the base-emitter voltage, V_{BE} , is selected so that no appreciable base current flows.



Figure 7.

I_{CM} DC collector peak current

It is the maximum collector current with sine-wave operation, $f \ge 25$ Hz, or pulse operation, $f \ge 25$ Hz, having a duty cycle of $t_p/T \le 0.5$

I_D, I_{DSS} Drain current

I_E Emitter current

I_{EBO}

Emitter cut-off current, with open collector

Emitter-base cut-off current, I_{EBO} , and emitter-base voltage, V_{EBO} , with open collector, i.e., $I_C = 0$



Figure 8.

 $\pm I_{G1/2SM}$ Gate 1/gate 2-source peak current

 $\pm I_{G1S/1SS}$ Gate 1-source current

 $\pm I_{G2S/2SS}$ Gate 2-source current

Input current

I_K Short-circuit current

I_Q Output current

I_S Supply current

K Kelvin

I

Length, connecting lead length

L_s Series inductance

M_A Tighto

Tightening torque

m Degree of modulation

Р

Power

P_I Input power

P_q, P_Q Output power

P_{tot}

Total power dissipation

It is the dispersion of the heat generated within a device when a current flows through it. The permissible power dissipation, $\mathsf{P}_{totmax,}$ which is specified under absolute maximum ratings, is a



function of T_{jmax} , T_{amb} , R_{thJA} and R_{thJC} . It is given as follows:

$$P_{\text{totmax}} \text{ (amb)} = \frac{T_{\text{jmax}} - T_{\text{amb}}}{R_{\text{thJA}}}$$

or

 $P_{totmax} (package) = \frac{T_{jmax} - T_{case}}{R_{thJC}}$

If the safe-operation conditions as given in the data sheets are observed, the power dissipation is limited (valid for special packages).

P_v Power dissipation, general

r_{bb}, Basic intrinsic resistance

 $\mathsf{R}_{\mathsf{B}\mathsf{E}}$ Resistance connected between base and emitter

DC forward resistance

r_f

Differential forward resistance

R_G Generator resistance

r_i Input resistance

R_L Load resistance

r_p Parallel resistance, damping resistance

r_o Output resistance

R_{thCA} Thermal resistance, channel ambient

R_{thJA} Thermal resistance, junction ambient

R_{thJC} Thermal resistance, junction case

s Standing wave ratio (SWR)

S, s Source

 $|S_{\rm 21e}|$ Forward transmission factor T

Period

Absolute temperature, Kelvin temperature 0 K = −273.15°C Unit: K (Kelvin) Т Temperature, measured in celsius Unit: °C t Time Tamb Ambient temperature If self-heating is significant: Temperature of the surrounding air below the device under conditions of thermal equilibrium If self-heating is insignificant: Air temperature in the immediate surroundings of the device Tamb Ambient temperature range As an absolute maximum rating: The maximum permissible ambient temperature range T_{c} Channel temperature T_{case} Case temperature The temperature measured at a specified point on the package of a semiconductor device Unless otherwise stated, this temperature is given as the temperature of the mounting base for transistors with metal can td Delay time, see section "Switching Characteristics" Fall time, see section "Switching Characteristics" t_{fr} Forward recovery time Τi Junction temperature It is the spatial mean value of the temperature which the junction has acquired during operation. In the case of transistors, it is mainly the temperature of the collector junction because its inherent temperature is maximum T_{K} Temperature coefficient The ratio of the relative change of an electrical quantity

to the change in temperature (Δt) which causes it,

under otherwise constant operating conditions



tL

Connecting lead temperature in holder at a distance, I, from case

t_{off}

Turn-off time, see section "Switching Characteristics"

t_{on} Turn-on time, see section "Switching Characteristics"

t_p Pulse duration

<u>t</u>р Т

Duty cycle

τ_r Rise time, see section "Switching Characteristics"

t_{rr} Reverse recovery time

ts Storage time, see section "Switching Characteristics"

t_{sd} Soldering temperature

Maximum permissible temperature for soldering with a specified distance from package and its duration. Refer to section "soldering instructions"

T_{stg} Storage temperature range

The temperature range at which the device may be stored or transported without any applied voltage

V_{BB} Base supply voltage

V_{BE} Base emitter voltage

V_{BEsat} Base saturation voltage

The base-emitter saturation voltage, V_{BEsat} , is the base-emitter voltage which belongs to the collector-emitter saturation voltage, V_{CEsat}

V_(BR) Breakdown voltage

Reverse voltage at which an increase in voltage results in a sharp rise of the reverse current. It is given in the technical data sheets for a specified current

 $V_{(BR)CBO}$ Breakdown voltage, collector-base, open emitter

V_{(BR)CEO}

Breakdown voltage, collector emitter, open base

Measurements with pulsed current collector source

With a switched-off inductive-load connected test circuit as shown in fig. 16 (see next page), it is set in breakdown position till the storage energy during switch-on has been discharged. This is when the ramp-shaped pulse current inflow at collector has reached its zero value.

Absolute maximum ratings of $V_{(BR)CEO}$ are defined with the test current, $I_{test},$ whereas the transistor has its lowest breakdown voltage value

The breakdown voltage and collector inductance has been dimensioned so that the load of breakdown energy is below the value of transistor failure

V_{(BR)CEV} Collector-emitter breakdown voltage at a defined reverse voltage between base and emitter

V_{(BR)DS} Drain-source breakdown voltage

V_{(BR)EBO} Breakdown voltage, emitter-base, open collector

 $V_{(BR)ECO}$ Breakdown voltage, emitter-collector, open base

 $\pm V_{(BR)G1SS}$ Gate 1-source breakdown voltage

 ${}^{\pm V}_{(BR)G2SS}$ Gate 2-source breakdown voltage

V_{CB} Collector-base voltage

V_{CBO} Collector-base voltage, open emitter

Generally, reverse biasing is the voltage applied to any of the two terminals of a transistor in such a way that one of the junctions operates in reverse direction, whereas the third terminal (second junction) is specified separately

V_{CC} Collector supply voltage

V_{CE}

Collector-emitter voltage

V_{CEO} Collector-emitter voltage, open base

V_{CER}

Collector-emitter voltage with a resistor R_{BE} connected between base and emitter

VCES

Collector-emitter voltage, short circuit between base and emitter

Vishay Telefunken 96 11935 1 I_{C} 0 $V_{s2} = 10 V$ I_{C measure} I_C L_C I_{B} Î \leftarrow $V_{S1} = 0$ to 30 V V_{CE} 5 V \bigcirc V_{(BR)CEO} 3 Pulses V_(BR)CEO I_{(BR)R} $\frac{t_p}{T} = 0.1$ $t_p = 10 \text{ ms}$ **1**00 mΩ Figure 9.



Figure 10. Typical voltage-breakdown behavior of a transistor



V_{CEsat}

Saturation voltage, collector emitter

The collector saturation voltage is the DC voltage between collector and emitter for specified saturation conditions.

The saturation voltage V_{CEsat} is given:

a) For a specified value of I_C where the base-emitter voltage equals the collector-emitter voltage, i.e., $V_{CB} = 0 V$





b) For a specified value of I_C and I_B where the operating point is in the saturation region, i.e., $V_{CE} < V_{CB}$



Figure 12.

c) For a specified value of the characteristic curve (I_B const.) which intersects the curve point I_C ' = K I_c (K = 1.1) and a specified value of the collector-emitter voltage (V_{CE} = 1 V)



Figure 13.

V_{CEsatHF} Collector-emitter HF saturation voltage

V_{CEV}

Collector-emitter voltage, with reverse base emitter voltage

V_{DS}

Drain source voltage, maximum

V_{EBO}

Emitter-base voltage, with open collector

V_F

Forward voltage

Emitter-base voltage due to the flow of the forward current at emitter-base juction

V_{G1S(OFF)} Gate 1-source cut-off voltage

V_{G2S(OFF)} Gate 2-source cut-off voltage

V_{HF} RF voltage, RMS value

V_{HF} RF voltage, peak value

Noise voltage (RMS value)

VR

Reverse voltage

Voltage drop which results from the flow of the reverse current

An external voltage applied to a semiconductor PN or NP junction to reduce the flow of current across the junction and thereby widen the depletion region

V_s Supply voltage

VT

Voltage due to temperature

The admittance matrix is an arrangement of y parameters given as follows:

$$y \;=\; \left(\begin{matrix} y_i \; y_r \\ y_f \; y_o \end{matrix} \right) \;=\; \left(\begin{matrix} y_{11} \; y_{12} \\ y_{21} \; y_{22} \end{matrix} \right)$$

y parameters are the coefficients of two-port network equations given in admittance form:

$$\underline{I}_{1} = y_{i} \underline{V}_{1} + y_{r} \underline{V}_{2} = y_{11} \underline{V}_{1} + y_{12} \underline{V}_{2}$$
$$\underline{I}_{1} = y_{i} \underline{V}_{1} + y_{r} \underline{V}_{2} = y_{11} \underline{V}_{1} + y_{12} \underline{V}_{2}$$
$$Y_{i}$$

Υi

Short-circuit input admittance

 $\mathbf{y}_{i} = \mathbf{y}_{11} = \left(\frac{\underline{\mathbf{I}}_{1}}{\underline{\mathbf{V}}_{1}}\right) \quad \underline{\mathbf{V}}_{2} = \mathbf{0}$

Parameter values are circuit-configuration dependent; therefore, a further subscript (e, b or c) is used to identify the circuit configuration

У_{ib}

Short-circuit input admittance in common-base configuration (small-signal value)

 $y_{ib} = g_{ib} + j \omega C_{ib}$

Уie

Short-circuit input admittance in common-emitter configuration (small-signal value)

 $y_{ie} = g_{ie} + j \omega C_{ie}$

Уr Short-circuit reverse-transfer admittance

$$y_r = y_{12} = \left(\frac{\underline{I}_1}{\underline{V}_2}\right) \underline{V}_1 = 0$$

y_{rb}

Short-circuit reverse-transfer admittance in common-base configuration (small-signal value)

$$y_{rb} = |y_{rb}| \exp \varphi_{rb}$$
$$= g_{rb} + j \omega C_{rb}$$

y_{re}

Short-circuit reverse-transfer admittance in common-emitter configuration (small-signal value)

Short-circuit forward-transfer admittance

$$\mathbf{y}_{\mathrm{f}} = \mathbf{y}_{21} = \left(\frac{\underline{\mathbf{I}}_2}{\underline{\mathbf{V}}_1}\right) \quad \underline{\mathbf{V}}_2 = \mathbf{0}$$

y_{fb}

Short-circuit forward-transfer admittance in common-base configuration (small-signal value)

 $y_{fb} = |y_{fb}| \exp \phi_{fb}$

Short-circuit forward-transfer admittance in common-emitter configuration (small-signal value)

$$y_{fe} = |y_{fe}| \exp \varphi_{fe}$$

y_{fs} Short-circuit forward admittance in a source configuration at a given operating point and frequency

y_o Short-circuit output admittance

$$\mathbf{y}_{0} = \mathbf{y}_{22} = \left(\frac{\underline{\mathbf{I}}_{2}}{\underline{\mathbf{V}}_{2}}\right) \quad \underline{\mathbf{V}}_{1} = \mathbf{0}$$

Yob

Short-circuit output admittance in common-base configuration (small-signal value)

$$y_{ob} = g_{ob} + j \omega C_{ob}$$

y_{oe}

Short-circuit output admittance in common-emitter configuration (small-signal value)

 $y_{oe} = g_{oe} + j \omega C_{oe}$

The following electrical characteristics can be calculated from the admittance parameters mentioned above.



Figure 14.

Current amplification

$$G_{i} = \frac{\underline{I}_{2}}{\underline{I}_{1}} = \frac{y_{21}}{y_{11}} \frac{Y_{L}}{(y_{22} + Y_{L}) - y_{12}y_{21}}$$





Voltage amplification

$$G_u = \frac{\underline{V}_2}{\underline{V}_1} = \frac{-y_{21}}{y_{22} + Y_L}$$

Input admittance

$$y_{in} = \frac{\underline{I}_1}{\underline{V}_1} = y_{11} - \frac{y_{12} \ y_{21}}{y_{22} + Y_L}$$

Output admittance

$$y_{out} = \frac{\underline{I}_2}{\underline{V}_2} = y_{22} - \frac{y_{12} \ y_{21}}{y_{11} + Y_G}$$

Power gain

$$G_{p} = \frac{P_{out} G_{L}}{P_{in} g_{in}} |A_{u}|^{2}$$
$$= \frac{G_{L}}{g_{in}} \left| \frac{y_{21}}{y_{22} + Y_{L}} \right|^{2}$$

At AF in certain cases, and for RF throughout, the coefficients of y parameters or the equivalent circuit according to Giacoletto (see section "Transistor Equivalent Circuit") are used. The y coefficients are valid only for a specified operating point and a specified frequency with narrow (frequency) range.

The y parameters are sometimes given separately as real and imaginary values or according to its modulus and phase.

 $y_i = g_i + j \omega C_i$

Short-circuit input conductance

Ci

Short-circuit input capacitance

 $y_r = g_r + j\omega C_r = |y_r| exp (j\phi_r)$

Short-circuit reverse conductance

Cr

Short-circuit reverse capacitance

y_r

Modulus of the short-circuit reverse-transfer admittance

 ϕ_r

Phase of the short-circuit reverse-transfer admittance

 $y_f = |y_f| \exp(j \phi_f)$

y_f

Modulus of short-circuit forward-transfer the admittance

Ψf

Phase of the short-circuit forward-transfer admittance

 $y_o = g_o + j \phi C_o$ g_o Short-circuit output conductance Co Short-circuit output capacitance Υ_G Generator admittance Phase angle φfb Phase of the short-circuit forward transfer admittance Уfb ϕ_{fe} Phase of the short-circuit forward transfer admittance **y**fe φ_{rb} Phase of the short-circuit reverse transfer admittance Уrb Υ_G Generator admittance CO Phase angle φfb Phase of the short-circuit forward-transfer admittance Уfb ϕ_{fe} Phase of the short-circuit forward-transfer admittance Уfb ϕ_{rb} Phase of the short-circuit reverse-transfer admittance Уrb ϕ_{re} Phase of the short-circuit reverse-transfer admittance Уre - Thermal Resistance for Pulse Cond. (K/W) 10 $t_{\rm p}/T = 0.5$ 1

0.2

0.1

0.05 0.1

0.0

0.01

0.01

 $\mathbf{Z}_{\mathrm{thp}}$

95 9918

0.01

0.1

1

Figure 15.

t_p – Pulse Length (ms)

100

10



Z_{thP} Thermal impedance, pulse load To determine the maximum power dissipation, $\mathsf{P}_{totmax},$ of a transistor by repetitive rectangular pulse operation, the calculation is as follows:

$$P_{totM} = \frac{T_{jM} - T_{case}}{Z_{thP}}$$

whereas:

 $T_{jmax} \stackrel{\circ}{=} T_{jM} =$

maximum (crest) permissible crystal temperature by repetitive pulse operation,

$$P_{totM} = \frac{T_{jmax} - T_{case}}{Z_{thP}}$$

 Z_{thP} = thermal impedance, pulse operation,

 $\frac{t_p}{T}$ as a parameter

When the calculation has been completed, $\mathsf{P}_{tot\ max}$ should correspond with the maximum permissible operating range.

π Efficiency

 T_{S} Storage-time constant





Switching Characteristics

By using a transistor as a switch, one has to bear in mind that during transition from off- to on-state, the signal does not respond instantaneously, even when abrupt changes in control values occur. The output signal is not only delayed but also distorted. These switching characteristics of a transistor are explained by means of an NPN transistor.

Figure 16 shows the basic circuit.



Figure 16.

The input (i.e., base current, i_B) and output (i.e., collector current, i_C) signals are shown in figure 17.



The transient responses as shown in figure 17 are given as follows:

t _d	: delay time
t _r	: rise time
$t_{on} (t_d + t_r)$: turn-on time
t _s	: storage time
t _f	: fall time
$t_{off} (t_s + t_f)$: turn-off time

These switching characteristics depend on the transistor type and the circuit used. They are only valid

if the slope of the control pulse is much greater than that of the collector current pulse. If the saturation factor is higher, the turn-on time is shorter, and the turn-off time is longer. The turn-off time is shorter if the on-off base current ratio is higher.